# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT	
NATURE OF CONVEYANCE:	Corrective Assignment to correct the spelling of second inventor's name and address of assignee previously recorded on Reel 014817 Frame 0272. Assignor (s) hereby confirms the Assignment by inventors to Taiwan Semiconductor Manufacturing Company, Ltd	

## **CONVEYING PARTY DATA**

Name	Execution Date
Ruei-chin Luo	11/26/2003
Samuel Chiang	11/26/2003
Chen-han Lien	11/26/2003

### RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

# PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10659848

### **CORRESPONDENCE DATA**

Fax Number: (214)200-0853

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 972-739-8635

Email: ipdocketing@haynesboone.com

Correspondent Name: Haynes and Boone, LLP
Address Line 1: 901 Main Street, Suite 3100
Address Line 4: Dallas, TEXAS 75202

NAME OF SUBMITTER: David M. O'Dell

Total Attachments: 3

PATENT REEL: 014894 FRAME: 0746

500003140

E HO

source=assignment#page1.tif source=assignment#page2.tif source=assignment#page3.tif

> PATENT REEL: 014894 FRAME: 0747

#### ASSIGNMENT

WHEREAS, we,

(1) Ruei-chin Luo of No 23, Ren-Chung Street
San-Chung City, Taiwan
Republic of China

(2) Samuel Chiang of 2n Floor, #1, 34<sup>th</sup> Lane
Da-chi Street
Taipei, Taiwan
Republic of China

(3) Chen-han Lien

of Chen-han Lien

No. 36-14, Dunung Tsuen
Liouying Shiang
Tainan, Taiwan 736
Republic of China

have invented certain improvements in

# GENERAL PURPOSE MEMORY COMPILER SYSTEM AND ASSOCIATED METHODS

for which we have filed an application for Letters Patent of the United States of America on September 11, 2003 under United States Patent Application Serial Number 10/659,848; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

PATENT

REEL: 014894 FRAME: 0748

Patent / Docket No. 24061.78 Customer No. 27683

. AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Residence Address:	Ruei-chin Luo No. 23, Ren-Chung Stre San-Chung City Taipei County, Taiwan,	
Dated: <sup>∨</sup> <u>Mov, 26, 7</u>	605	Nuertor Signature
Dated: Nov. 26. 2	۵۰۶	Witness Signature Witness Name: CHING-WEI WU
Second Inventor Name: Residence Address:	Samuel Chiang 2n Floor, #1, 34 <sup>th</sup> Lane Da-chi Street Taipei, Taiwan	
Dated: Vov. 26, 2	2003	Sumuel Miane Inventor Signature
Dated: Nov. So,	<u> 2003</u>	Witness Signature Witness Name:

- 2 -

Patent / Docket No. 24061.78 Customer No. 27683

Third Inventor Name:

Chen-han Lien

Residence Address:

No. 336-14, Dunung Tsuen

Liouying Shiang

Tainan, Taiwan 736, R.O.C.

Dated: Nov. 26. 2003

捷達 chen-han Lien

Inventor Signature

Dated: N 1 1 200}

Witness Signature pei-Jiun Chen

Witness Name:\_

R51509.2

- 3 -

**PATENT REEL: 014894 FRAME: 0750**